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<u>MOSFET</u> – Power, Single, N-Channel

40 V, 2.3 mΩ, 140 A

NTMFS5C442N

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	40	V
Gate-to-Source Voltage			V _{GS}	±20	V
Continuous Drain	Steady State	$T_{C} = 25^{\circ}C$	I _D	140	А
Current R _{θJC} (Notes 1, 3)	Sidle	T _C = 100°C		99	
Power Dissipation		$T_{C} = 25^{\circ}C$	PD	83	W
$R_{\theta JC}$ (Note 1)		$T_C = 100^{\circ}C$		42	
Continuous Drain Current R _{0.IA}	Steady State	T _A = 25°C	Ι _D	29	А
(Notes 1, 2, 3)	Sidle	T _A = 100°C		21	
Power Dissipation		T _A = 25°C	PD	3.7	W
R _{θJA} (Notes 1 & 2)		$T_A = 100^{\circ}C$		1.8	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \ \mu s$		I _{DM}	900	А
Operating Junction and Storage Temperature			T _J , T _{stg}	–55 to + 175	°C
Source Current (Body Diode)			۱ _S	92	А
Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)} = 12 \text{ A}$)			E _{AS}	220	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

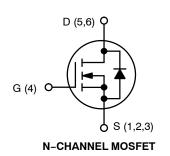
Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	1.8	°C/W
Junction-to-Ambient - Steady State (Note 2)	Reia	41	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	2.3 mΩ @ 10 V	140 A





ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

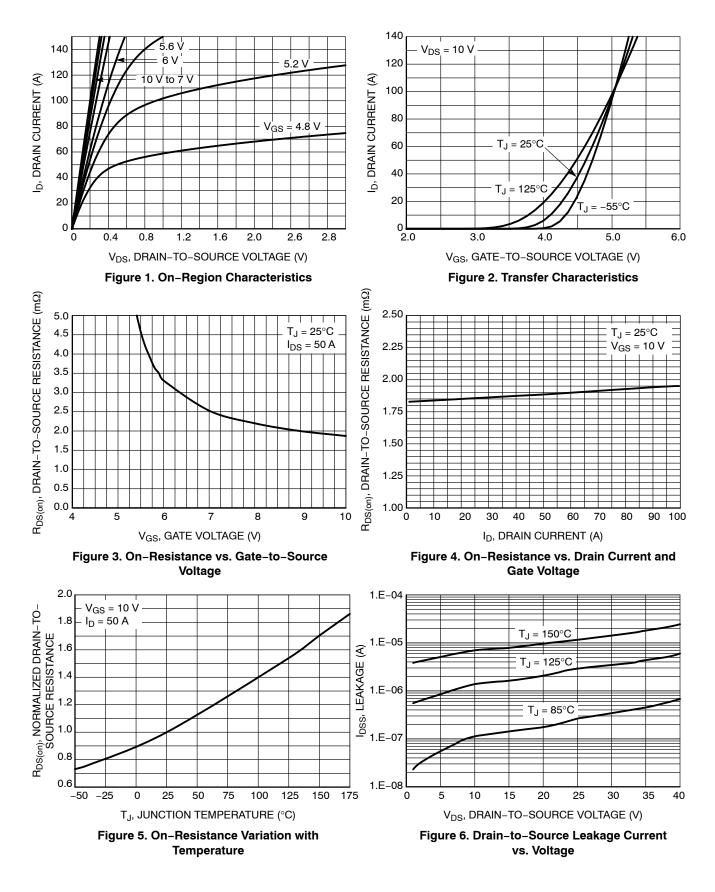
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ELECTRICAL CHARACTERISTICS (T_J = $25^{\circ}C$ unless otherwise specified)

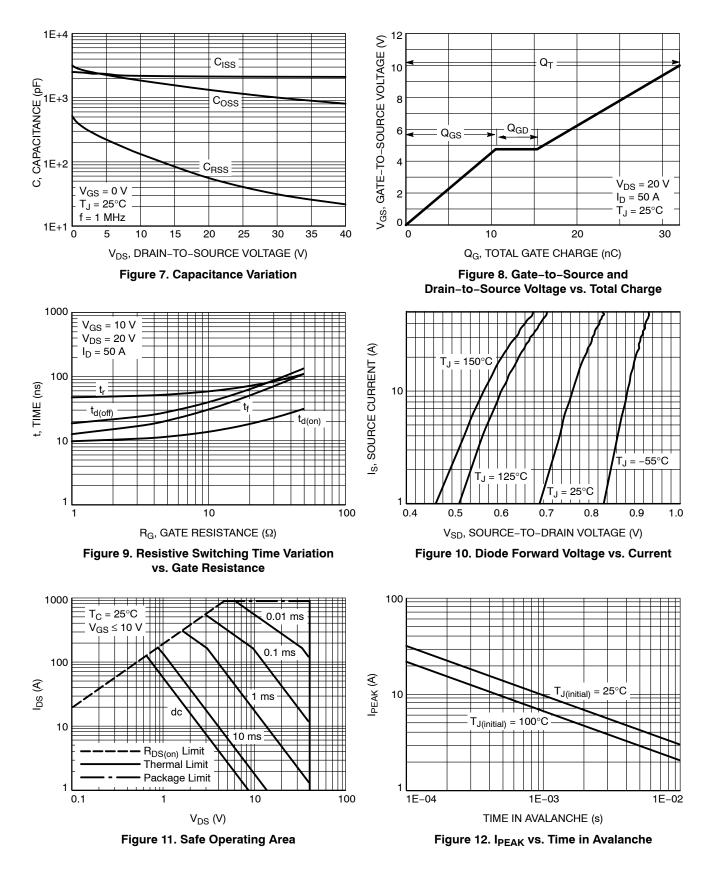
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 250 µA		40	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J			-	15.2	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V, V_{DS} = 40 V \qquad \frac{T_{J} = 25 °C}{T_{J} = 125 °C}$		-	-	10	μA
				-	-	250	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V		-	-	100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 90 μA	2.0	-	4.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J			-	-7.7	-	mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V I _D = 50 A		-	1.9	2.3	mΩ
Forward Transconductance	9 _{FS}	V _{DS} = 15 V, I _D = 50 A		-	92	-	S
CHARGES, CAPACITANCES & GATE RE	SISTANCE				-		-
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz	z, V _{DS} = 25 V	-	2100	-	pF
Output Capacitance	C _{OSS}			-	1100	-	
Reverse Transfer Capacitance	C _{RSS}			-	40	-	1
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 10 V, V_{DS} = 20 V; I_{D} = 50 A		-	32	-	nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 20 V; I _D = 50 A		-	6.6	-	1
Gate-to-Source Charge	Q _{GS}			-	11	-	
Gate-to-Drain Charge	Q _{GD}			-	4.7	-	1
Plateau Voltage	V _{GP}			-	4.7	-	V
SWITCHING CHARACTERISTICS (Note 5	i)				-		-
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DS} = 20 V, I_{D} = 50 A, R_{G} = 2.5 Ω		-	11	-	ns
Rise Time	tr			-	50	-	-
Turn-Off Delay Time	t _{d(OFF)}			-	23	-	
Fall Time	t _f			-	18	-	1
DRAIN-SOURCE DIODE CHARACTERIS	TICS						•
Forward Diode Voltage	ls = 50 A	$V_{GS} = 0 V,$ $T_J = 25^{\circ}C$	-	0.83	1.2	V	
		T _J = 125°C	C –	0.71	-		
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dI _S /dt = 100 A/µs, I _S = 50 A		-	43	-	ns
Charge Time	ta			-	22	-	1
Discharge Time	t _b			-	22	-	1
Reverse Recovery Charge	Q _{RR}			-	40	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS

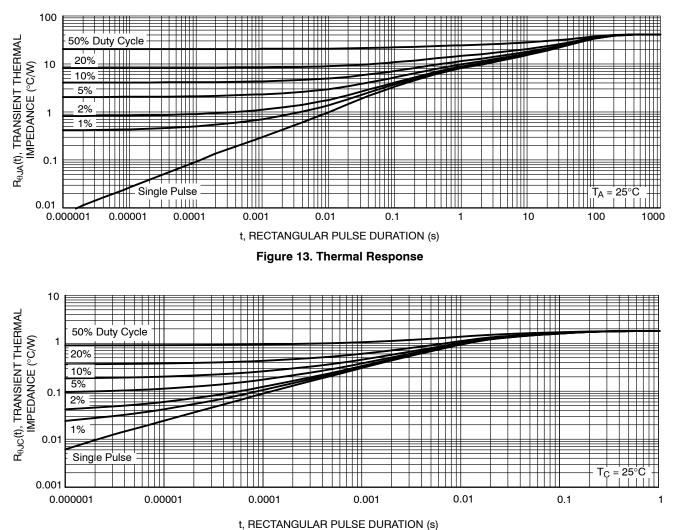


Figure 14. Thermal Response

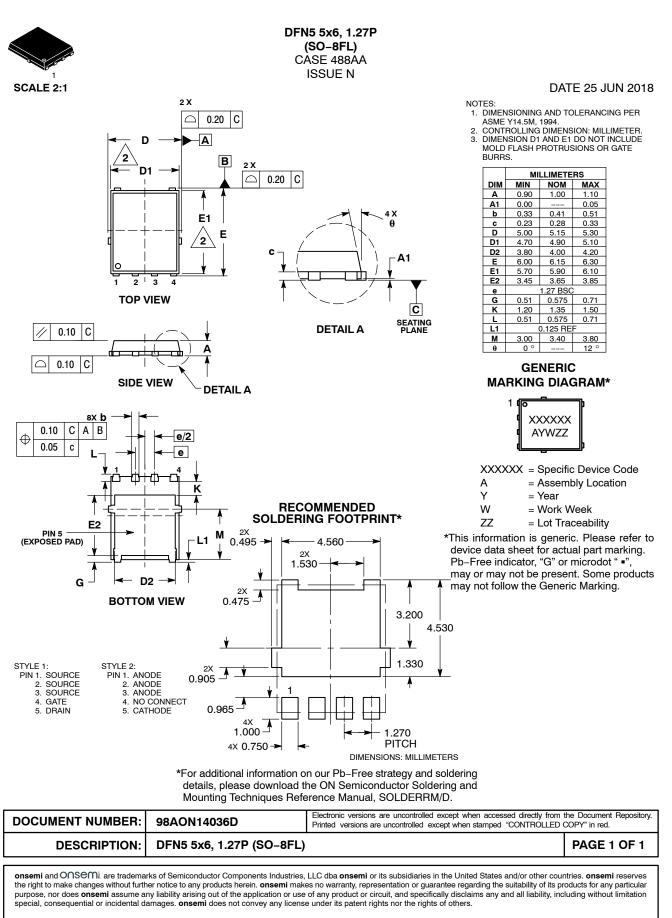
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS5C442NT1G	5C442N	DFN5 (Pb–Free)	1500 / Tape & Reel
NTMFS5C442NT3G	5C442N	DFN5 (Pb–Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <u>BRD8011/D</u>.

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